

ABSTRACT

To provide a mold release film which is not easily electrically charged or curled, does not contaminate a mold, and has excellent mold followability, a process for its production, and a process for producing a semiconductor package by using the mold release film. A mold release film to be disposed on a surface of a mold which is to be in contact with a curable resin, in a process for producing a semiconductor package by disposing a semiconductor element in the mold, and sealing it with the curable resin to form a resin sealed portion, comprising a first thermoplastic resin layer to be in contact with the curable resin at the time of forming the resin sealed portion, a second thermoplastic resin layer to be in contact with the mold at the time of forming the resin sealed portion, and an interlayer disposed between the first thermoplastic resin layer and the second thermoplastic resin layer, wherein the first thermoplastic resin layer and the second thermoplastic resin layer have a storage elastic modulus at 180°C of from 10 to 300 MPa, respectively, the difference in storage elastic modulus at 25°C between them is at most 1,200 MPa, and their thicknesses are from 12 to 50 μm , and the interlayer includes a layer containing a polymeric antistatic agent.